ELECTRICAL CHARACTERISTICS (CONTINUED)

Electrical Specifications: Unless otherwise indicated, V_{DD} = 5V, V_{SS} = 0V, V_{REF} = 2.048V, Output Buffer Gain (G) = 2x, R_L = 5 kΩ to GND, C_L = 100 pF T_A = -40 to +85°C. Typical values are at +25°C.

Parameters	Sym	Min	Typ	Max	Units	Conditions
Offset Error	V_{OS}	—	±0.02	1	% of FSR	Code = 0x000h
Offset Error Temperature Coefficient	V_{OS}/°C	—	0.16	—	ppm/°C	-45°C to 25°C
		—	-0.44	—	ppm/°C	+25°C to 85°C
Gain Error	g_E	—	-0.10	1	% of FSR	Code = 0xFFFh, not including offset error
Gain Error Temperature Coefficient	ΔG/°C	—	-3	—	ppm/°C	
Input Amplifier (V_{REF} Input)						
Input Range – Buffered Mode	V_{REF}	0.040	—	V_{DD} – 0.040	V	**Note 2** Code = 2048 V_{REF} = 0.2 Vp-p, f = 100 Hz and 1 kHz
Input Range – Unbuffered Mode	V_{REF}	0	—	V_{DD}	V	
Input Impedance	R_{VREF}	—	165	—	kΩ	Unbuffered Mode
Input Capacitance – Unbuffered Mode	C_{VREF}	—	7	—	pF	
Multiplier Mode -3 dB Bandwidth	f_{VREF}	—	450	—	kHz	V_{REF} = 2.5V ±0.2Vp-p, Unbuffered, G = 1
	f_{VREF}	—	400	—	kHz	V_{REF} = 2.5V ±0.2 Vp-p, Unbuffered, G = 2
Multiplier Mode – Total Harmonic Distortion	THD_{VREF}	—	-73	—	dB	V_{REF} = 2.5V ±0.2Vp-p, Frequency = 1 kHz
Output Amplifier						
Output Swing	V_{OUT}	—	0.01 to V_{DD} – 0.04	—	V	Accuracy is better than 1 LSb for V_{OUT} = 10 mV to (V_{DD} – 40 mV)
Phase Margin	θm	—	66	—	Degrees	
Slew Rate	SR	—	0.55	—	V/µs	
Short Circuit Current	I_{SC}	—	15	24	mA	
Settling Time	$t_{settling}$	—	4.5	—	µs	Within 1/2 LSB of final value from 1/4 to 3/4 full-scale range
Dynamic Performance (Note 2)						
DAC-to-DAC Crosstalk		—	10	—	nV-s	
Major Code Transition Glitch		—	45	—	nV-s	1 LSB change around major carry (0111...1111 to 1000...0000)
Digital Feedthrough		—	10	—	nV-s	
Analog Crosstalk		—	10	—	nV-s	

Note 1: Guaranteed monotonic by design over all codes.

2: This parameter is ensured by design, and not 100% tested.

AC CHARACTERISTICS (SPI TIMING SPECIFICATIONS)

Electrical Specifications: Unless otherwise indicated, V_{DD}= 2.7V – 5.5V, T_A= -40 to +125°C. Typical values are at +25°C.

Parameters	Sym	Min	Typ	Max	Units	Conditions
Schmitt Trigger High Level Input Voltage (All digital input pins)	V_{IH}	0.7 V_{DD}	—	—	V	
Schmitt Trigger Low Level Input Voltage (All digital input pins)	V_{IL}	—	—	0.2 V_{DD}	V	
Hysteresis of Schmitt Trigger Inputs	V_{HYS}	—	0.05 V_{DD}	—		
Input Leakage Current	$I_{LEAKAGE}$	-1	—	1	µA	$\overline{LDAC}$ = $\overline{CS}$ = SDI = SCK = V_{REF} = V_{DD} or V_{SS}
Digital Pin Capacitance (All inputs/outputs)	C_{IN}, C_{OUT}	—	10	—	pF	V_{DD} = 5.0V, T_A = +25°C, f_{CLK} = 1 MHz **(Note 1)**
Clock Frequency	F_{CLK}	—	—	20	MHz	T_A = +25°C **(Note 1)**
Clock High Time	t_{HI}	15	—	—	ns	**Note 1**
Clock Low Time	t_{LO}	15	—	—	ns	**Note 1**
$\overline{CS}$ Fall to First Rising CLK Edge	t_{CSSR}	40	—	—	ns	Applies only when $\overline{CS}$ falls with CLK high **(Note 1)**
Data Input Setup Time	t_{SU}	15	—	—	ns	**Note 1**
Data Input Hold Time	t_{HD}	10	—	—	ns	**Note 1**
SCK Rise to $\overline{CS}$ Rise Hold Time	t_{CHS}	15	—	—	ns	**Note 1**
$\overline{CS}$ High Time	t_{CSH}	15	—	—	ns	**Note 1**
$\overline{LDAC}$ Pulse Width	t_{LD}	100	—	—	ns	**Note 1**
$\overline{LDAC}$ Setup Time	t_{LS}	40	—	—	ns	**Note 1**
SCK Idle Time before $\overline{CS}$ Fall	t_{IDLE}	40	—	—	ns	**Note 1**

Note 1: This parameter is ensured by design and not 100% tested.

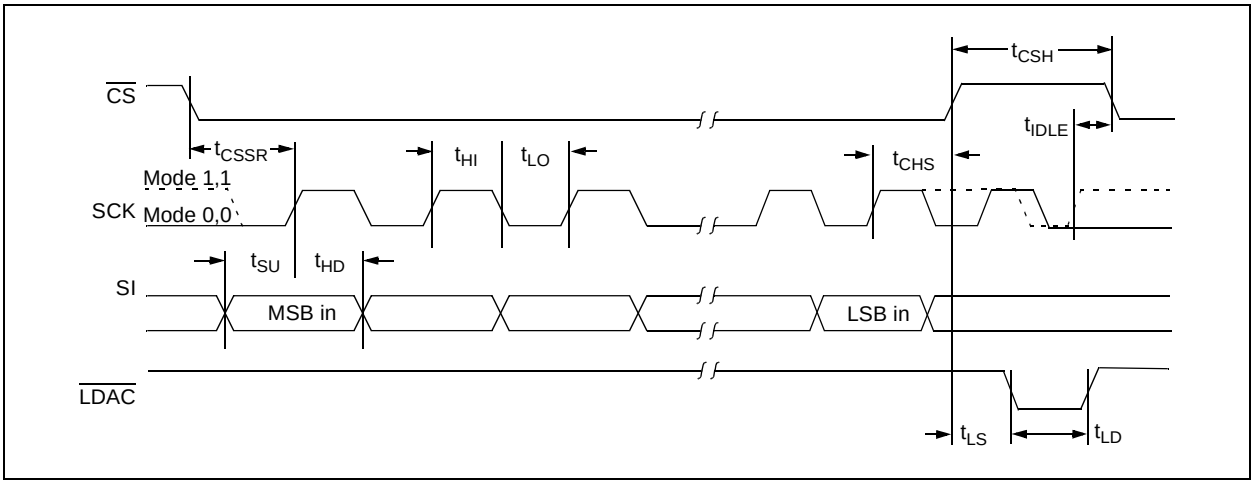

FIGURE 1-1: *SPI Input Timing Data.*

3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 3-1.

TABLE 3-1: PIN FUNCTION TABLE

PDIP, MSOP, SOIC	DFN	Symbol	Description
1	1	V_{DD}	Supply Voltage Input (2.7V to 5.5V)
2	2	$\overline{CS}$	Chip Select Input
3	3	SCK	Serial Clock Input
4	4	SDI	Serial Data Input
5	5	$\overline{LDAC}$	DAC Output Synchronization Input. This pin is used to transfer the input register (DAC settings) to the output register (V_{OUT})
6	6	V_{REF}	Voltage Reference Input
7	7	V_{SS}	Ground reference point for all circuitry on the device
8	8	V_{OUT}	DAC Analog Output
—	9	EP	Exposed Thermal Pad. This pad must be connected to V_{SS} in application

3.1 Supply Voltage Pins (V_{DD}, V_{SS})

V_{DD} is the positive supply voltage input pin. The input supply voltage is relative to V_{SS} and can range from 2.7V to 5.5V. The power supply at the V_{DD} pin should be as clean as possible for good DAC performance. It is recommended to use an appropriate bypass capacitor of about 0.1 µF (ceramic) to ground. An additional 10 µF capacitor (tantalum) in parallel is also recommended to further attenuate high-frequency noise present in application boards.

V_{SS} is the analog ground pin and the current return path of the device. The user must connect the V_{SS} pin to a ground plane through a low-impedance connection. If an analog ground path is available in the application Printed Circuit Board (PCB), it is highly recommended that the V_{SS} pin be tied to the analog ground path or isolated within an analog ground plane of the circuit board.

3.2 Chip Select ($\overline{CS}$)

$\overline{CS}$ is the chip select input, which requires an active-low signal to enable serial clock and data functions.

3.3 Serial Clock Input (SCK)

SCK is the SPI compatible serial clock input.

3.4 Serial Data Input (SDI)

SDI is the SPI compatible serial data input.

3.5 Latch DAC Input ($\overline{LDAC}$)

The $\overline{LDAC}$ (latch DAC synchronization input) pin is used to transfer the input latch register to the DAC register (output latches, V_{OUT}). When this pin is low, V_{OUT} is updated with input register content. This pin can be tied to low (V_{SS}) if the V_{OUT} update is desired at the rising edge of the $\overline{CS}$ pin. This pin can be driven by an external control device such as an MCU I/O pin.

3.6 Analog Output (V_{OUT})

V_{OUT} is the DAC analog output pin. The DAC output has an output amplifier. The full-scale range of the DAC output is from V_{SS} to G*V_{REF}, where G is the gain selection option (1x or 2x). The DAC analog output cannot go higher than the supply voltage (V_{DD}).

3.7 Voltage Reference Input (V_{REF})

V_{REF} is the voltage reference input for the device. The reference on this pin is utilized to set the reference voltage on the string DAC. The input voltage can range from V_{SS} to V_{DD}. This pin can be tied to V_{DD}.

3.8 Exposed Thermal Pad (EP)

There is an internal electrical connection between the Exposed Thermal Pad (EP) and the V_{SS} pin. They must be connected to the same potential on the PCB.

5.0 SERIAL INTERFACE

5.1 Overview

The MCP4901/4911/4921 devices are designed to interface directly with the Serial Peripheral Interface (SPI) port, which is available on many microcontrollers and supports Mode 0,0 and Mode 1,1. Commands and data are sent to the device via the SDI pin, with data being clocked-in on the rising edge of SCK. The communications are unidirectional, thus the data cannot be read out of the MCP4901/4911/4921. The $\overline{CS}$ pin must be held low for the duration of a write command. The write command consists of 16 bits and is used to configure the DAC's control and data latches. Register 5-1 through Register 5-3 detail the input register that is used to configure and load the DAC register for each device. Figure 5-1 through Figure 5-3 show the write command for each device.

Refer to Figure 1-1 and the SPI Timing Specifications Table for detailed input and output timing specifications for both Mode 0,0 and Mode 1,1 operation.

5.2 Write Command

The write command is initiated by driving the $\overline{CS}$ pin low, followed by clocking the four Configuration bits and the 12 data bits into the SDI pin on the rising edge of SCK. The $\overline{CS}$ pin is then raised, causing the data to be latched into the DAC's input register.

The MCP4901/4911/4921 utilizes a double-buffered latch structure to allow the analog output to be synchronized with the $\overline{LDAC}$ pin, if desired.

By bringing the $\overline{LDAC}$ pin down to a low state, the content stored in the DAC's input register is transferred into the DAC's output register (V_{OUT}), and V_{OUT} is updated.

All writes to the MCP4901/4911/4921 devices are 16-bit words. Any clocks past the 16th clock will be ignored. The Most Significant 4 bits are Configuration bits. The remaining 12 bits are data bits. No data can be transferred into the device with $\overline{CS}$ high. This transfer will only occur if 16 clocks have been transferred into the device. If the rising edge of $\overline{CS}$ occurs prior to that, shifting of data into the input register will be aborted.

REGISTER 5-1: WRITE COMMAND REGISTER FOR MCP4921 (12-BIT DAC)

W-x	W-x	W-x	W-0	W-x	W-x	W-x	W-x	W-x	W-x	W-x	W-x	W-x	W-x	W-x	W-x
0	BUF	$\overline{GA}$	$\overline{SHDN}$	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
bit 15															bit 0

REGISTER 5-2: WRITE COMMAND REGISTER FOR MCP4911 (10-BIT DAC)

W-x	W-x	W-x	W-0	W-x	W-x	W-x	W-x	W-x	W-x	W-x	W-x	W-x	W-x	W-x	W-x
0	BUF	$\overline{GA}$	$\overline{SHDN}$	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	x	x
bit 15															bit 0

REGISTER 5-3: WRITE COMMAND REGISTER FOR MCP4901 (8-BIT DAC)

W-x	W-x	W-x	W-0	W-x	W-x	W-x	W-x	W-x	W-x	W-x	W-x	W-x	W-x	W-x	W-x
0	BUF	$\overline{GA}$	$\overline{SHDN}$	D7	D6	D5	D4	D3	D2	D1	D0	x	x	x	x
bit 15															bit 0

Where:

bit 15 0 = Write to DAC register
1 = Ignore this command

bit 14 **BUF:** V_{REF} Input Buffer Control bit
1 = Buffered
0 = Unbuffered

bit 13 **$\overline{GA}$:** Output Gain Selection bit
1 = 1x ($V_{OUT} = V_{REF} * D/4096$)
0 = 2x ($V_{OUT} = 2 * V_{REF} * D/4096$)

bit 12 **$\overline{SHDN}$:** Output Shutdown Control bit
1 = Active mode operation. VOUT is available.
0 = Shutdown the device. Analog output is not available. VOUT pin is connected to 500 kΩ (typical).

bit 11-0 **D11:D0:** DAC Input Data bits. Bit x is ignored.

Legend			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	1 = bit is set	0 = bit is cleared	x = bit is unknown

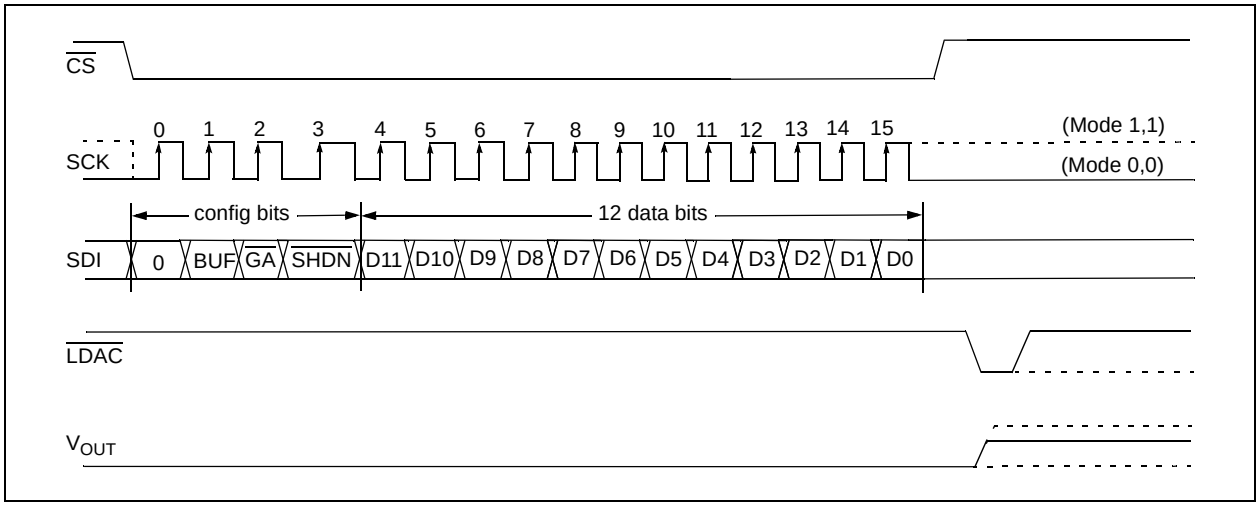

FIGURE 5-1: *Write Command for MCP4921 (12-bit DAC).*

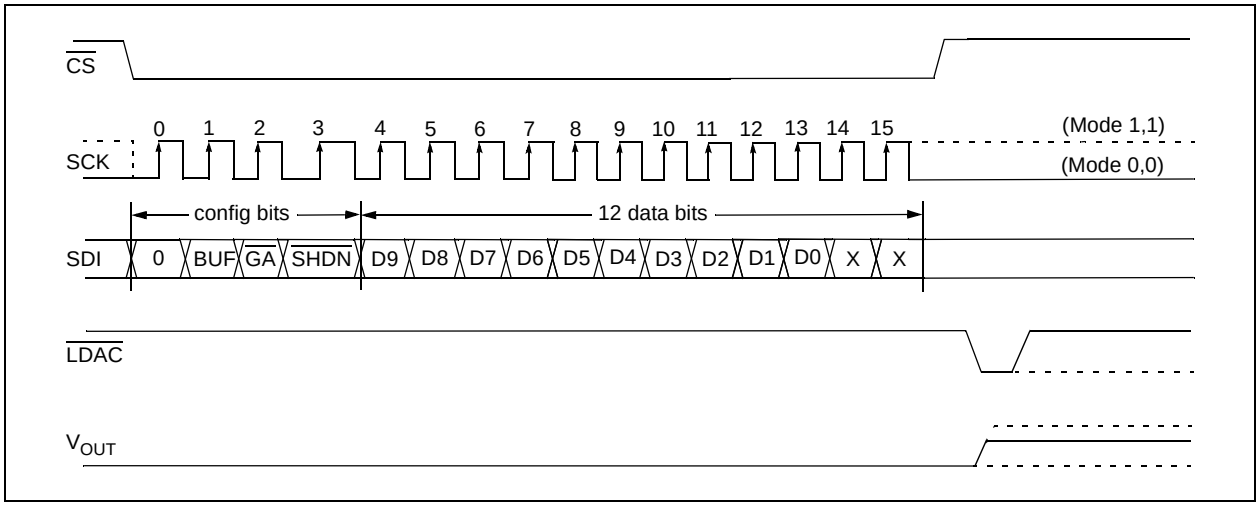

FIGURE 5-2: *Write Command for MCP4911 (10-bit DAC). Note: X are don't care bits.*

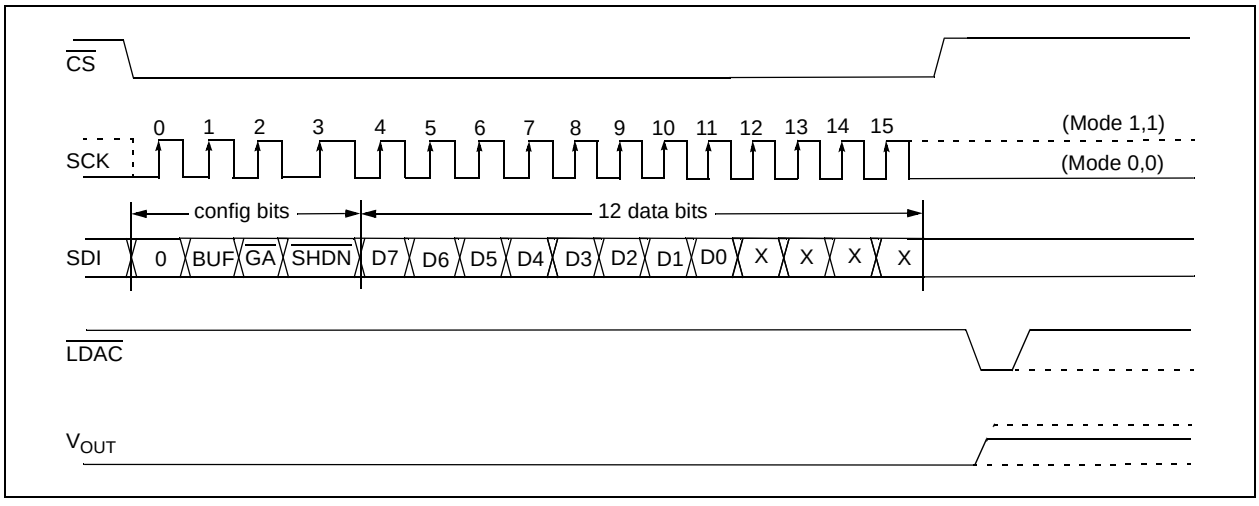

FIGURE 5-3: *Write Command for MCP4901(8-bit DAC). Note: X are don't care bits.*